



17 November 2005

To: Frank Ruffino, (Chairman EIA CE2.0)
Carl Fritz, (Secretary EIA CE2.0)

From: Jeff Toran, (Deputy Technical Advisor for IEC TC48/SC48B)

RE: IEC Connector standards meetings 14-21 October 2005

Connector and test method related items, TC48 and SC/WGs:

Attendees from the following connector companies – Tyco, Molex, FCI, Harting, DDK , JAE, JST, Nexans, Wago, Seimon, Belden, Reichle de-Massari, and Woodhead Connectivity.

- 1) Review & discussion of revisions to several of the Mod Jack standards (higher data rate information).
- 2) Discussed comments to industrial Ethernet standards being developed.
- 3) Discussed potential change of scope to Ed 2 of IEC 61984 Safety standard. This standard describes rules for rated voltage/current levels for connectors according to contact pitch, geometry and end-use environment. The scope change was NOT approved. Other comments to the Ed.2 document were discussed and resolved.
- 4) Jeff Toran discussed the need for more specific test schedules for ‘power contacts/connectors’. There is an EIA standard drafted that may be introduced to the IEC next spring.
- 5) Discussed a request from ISO/IEC/JTC1/SC25 regarding Power over Ethernet applications. The committee members would like SC48B to develop a ‘hot’ mating/unmating test. One of the German experts is going to prepare a draft for review in a few weeks.

Attachment No. 7

RoHS related items

1) Discussions in the SC48B Connector Test working group:

- Solderability test results versus inventory time. Tin has good solderability after 2 years in warehouse. FCI presented data and Tyco, Molex corroborated.
- Press-fit pin insertion/retention data for Lead-free products discussed. All agreed LF product has an average of 15% higher insertion force values.
- The IEC 60352-5 standard for press-fit pins will be revised to include LF information. Also, Jeff Toran proposed a revision to simplify the test boards required for qualification. The “concept” was accepted...draft proposal due in 6 weeks.

2) IEC TC91, “Electronics Assembly Technology’. This TC is Chaired by Dieter Bergman of the IPCs. The TC is developing several RoHS test methods that will be used by several other electronic component TCs, including the Connector group. As reported by the liaison person from SC48B (works for Tyco) the latest information is:

- LF/RoHS Standards in preparation (expected publication in 2007)
 1. whisker test methods – similar to iNEMI
 2. solderability test methods – wetting balance
 3. solder paste compositions
- New standard proposal from the IPC for standardized product marking & labeling for RoHS was NOT approved. FCI-CDC has not supported this proposal as it is too complex and cumbersome to implement.

3) IEC TC 111, “Environmental Aspects...” is also developing several RoHS related standards. This is a new TC and will pickup some of the work started by TC91 above. It is chaired by a person from Japan.

- new standard for ‘material declaration’ requirements – two competing proposals:
 1. Proposal by US to create an IEC standard using an existing EIA standard for 12 banned substances and 25 reportable substances.
 2. Proposal by Finland to require that all elements/compounds be reported for all items.
- chemical composition test methods and certified standards
- terminology/definitions standard